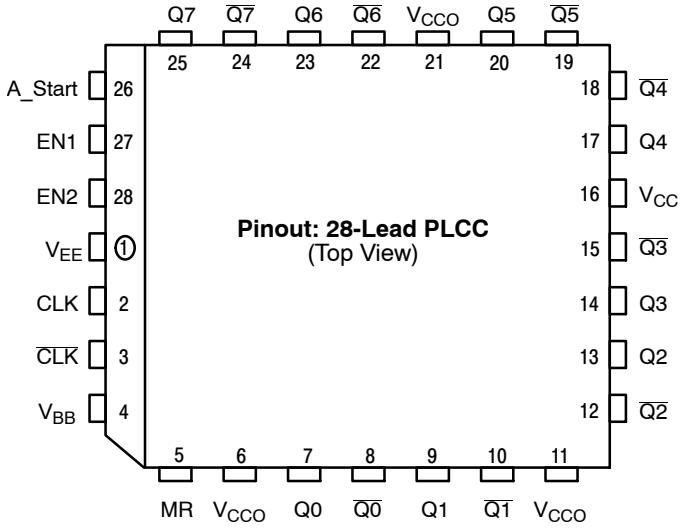

* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 28-Lead Pinout

Table 1. PIN DESCRIPTION

PIN	FUNCTION
CLK, $\overline{CLK}$	ECL Differential Clock Inputs
Q0-Q7, $\overline{Q0}$-$\overline{Q7}$	ECL Differential Q Outputs
A_Start	ECL Asynchronous Enable Input
EN1, EN2	ECL Synchronous Enable Inputs
MR	Asynchronous Master Reset
V_{BB}	Reference Voltage Output
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply

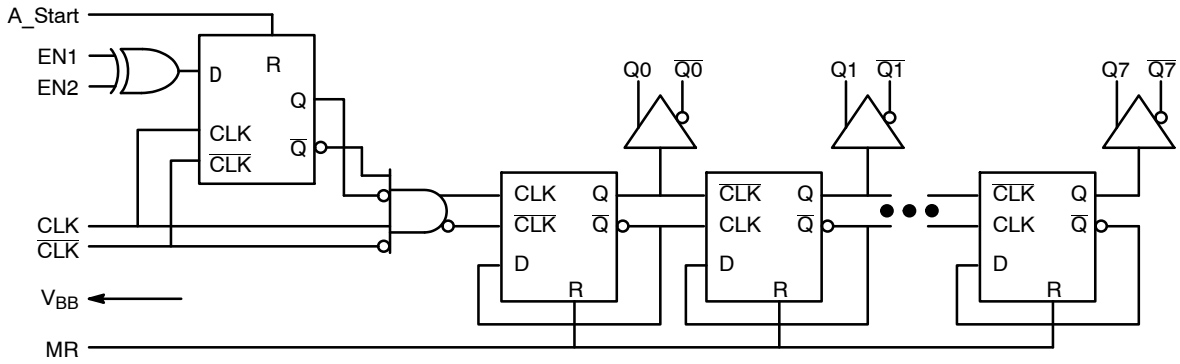

Figure 2. Logic Diagram

Table 2. SEQUENTIAL TRUTH TABLE

Function	EN1	EN2	A_Start	MR	CLK	Q7	Q6	Q5	Q4	Q3	Q2	Q1	Q0
Reset	X	X	X	H	X	L	L	L	L	L	L	L	L
Count	L	L	L	L	Z	L	L	L	L	L	L	L	H
	L	L	L	L	Z	L	L	L	L	L	L	H	L
	L	L	L	L	Z	L	L	L	L	L	L	H	H
Stop	H	L	L	L	Z	L	L	L	L	L	L	H	H
	H	L	L	L	Z	L	L	L	L	L	L	H	H
Asynch Start	H	L	H	L	Z	L	L	L	L	L	H	L	L
	H	L	H	L	Z	L	L	L	L	L	H	L	H
	L	L	H	L	Z	L	L	L	L	L	H	H	L
Count	L	L	L	L	Z	L	L	L	L	L	H	H	H
	L	L	L	L	Z	L	L	L	L	H	L	L	L
	L	L	L	L	Z	L	L	L	L	H	L	L	H
Stop	L	H	L	L	Z	L	L	L	L	H	L	L	H
	L	H	L	L	Z	L	L	L	L	H	L	L	H
Synch Start	H	H	L	L	Z	L	L	L	L	H	L	H	L
	H	H	L	L	Z	L	L	L	L	H	L	H	H
	H	H	L	L	Z	L	L	L	L	H	H	L	L
Stop	H	L	L	L	Z	L	L	L	L	H	H	L	L
	H	L	L	L	Z	L	L	L	L	H	H	L	L
Count	L	L	L	L	Z	L	L	L	L	H	H	L	H
	L	L	L	L	Z	L	L	L	L	H	H	H	L
	L	L	L	L	Z	L	L	L	L	H	H	H	H
Reset	X	X	X	H	X	L	L	L	L	L	L	L	L

Z = Low to High Transition

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		−8	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 −6	V
I_{out}	Output Current	Continuous Surge		50 100	mA
T_A	Operating Temperature Range			0 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC−28	63.5 43.5	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC−28	22 to 26	°C/W
V_{EE}	PECL Operating Range NECL Operating Range			4.2 to 5.7 −5.7 to −4.2	V
T_{sol}	Wave Solder (Pb-Free)			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. 10E SERIES PECL DC CHARACTERISTICS (V_{CCx} = 5.0 V; V_{EE} = 0.0 V (Note 1))

Symbol	Characteristic	0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		121	145		121	145		121	145	mA
V_{OH}	Output HIGH Voltage (Note 2)	3980	40 70	4160	4020	4105	4190	4090	4185	4280	mV
V_{OL}	Output LOW Voltage (Note 2)	3050	3210	3370	3050	3210	3370	3050	3227	3405	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	3830	3995	4160	3870	4030	4190	3940	4110	4280	mV
V_{IL}	Input LOW Voltage (Single-Ended)	3050	3285	3520	3050	3285	3520	3050	3302	3555	mV
V_{BB}	Output Voltage Reference	3.62		3.73	3.65		3.75	3.69		3.81	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.2		4.6	2.2		4.6	2.2		4.6	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 5. 10E SERIES NECL DC CHARACTERISTICS (V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note 1))

Symbol	Characteristic	0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		121	145		121	145		121	145	mA
V_{OH}	Output HIGH Voltage (Note 2)	−1020	−930	−840	−980	−895	−810	−910	−815	−720	mV
V_{OL}	Output LOW Voltage (Note 2)	−1950	−1790	−1630	−1950	−1790	−1630	−1950	−1773	−1595	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	−1170	−1005	−840	−1130	−970	−810	−1060	−890	−720	mV
V_{IL}	Input LOW Voltage (Single-Ended)	−1950	−1715	−1480	−1950	−1715	−1480	−1950	−1698	−1445	mV
V_{BB}	Output Voltage Reference	−1.38		−1.27	−1.35		−1.25	−1.31		−1.19	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	−2.8		−0.4	−2.8		−0.4	−2.8		−0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.065		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 6. AC CHARACTERISTICS (V_{CCx} = 5.0 V; V_{EE} = 0.0 V or V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note NO TAG))

Symbol	Characteristic	0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{COUNT}	Maximum Count Frequency	1800	2200		1800	2200		1800	2200		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output CLK to Q0 CLK to Q1 CLK to Q2 CLK to Q3 CLK to Q4 CLK to Q5 CLK to Q6 CLK to Q7 A_Start to Q0 MR to Q0	 1300 1600 1950 2275 2625 2950 3250 3575 950 700	 1700 2025 2425 2750 3125 3450 3775 4075 1325 1000	 2150 2500 2925 3350 3750 4150 4450 4800 1700 1300	 1300 1600 1950 2275 2625 2950 3250 3575 950 700	 1700 2050 2450 2775 3150 3475 3800 4125 1325 1000	 2150 2500 2925 3350 3750 4150 4450 4800 1700 1300	 1350 1650 2025 2350 2700 3050 3375 3700 950 700	 1750 2100 2500 2850 3225 3550 3925 4250 1325 1000	 2200 2550 3000 3425 3825 4250 4600 4950 1700 1300	ps
t_s	Setup Time (EN1, EN2)	0	−150		0	−150		0	−150		ps
t_h	Hold Time (EN1, EN2)	300	150		300	150		300	150		ps
t_{RR}	Reset Recovery Time MR, A_Start	400	200		400	200		400	200		ps
t_{PW}	Minimum Pulse Width CLK, MR, A_Start	400			400			400			ps
V_{PP}	Input Voltage Swing CLK/$\overline{CLK}$ (Differential Configuration) (Note 4)	0.25		1.0	0.25		1.0	0.25		1.0	V
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
t_r t_f	Rise/Fall Times (20%−80%) Q0,Q1 Q2 to Q7	 150 275		 400 600	 150 275		 400 600	 150 275		 400 600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

4. Minimum input swing for which AC parameters are guaranteed. Full DC ECL output swings will be generated with only 50 mV input swings.

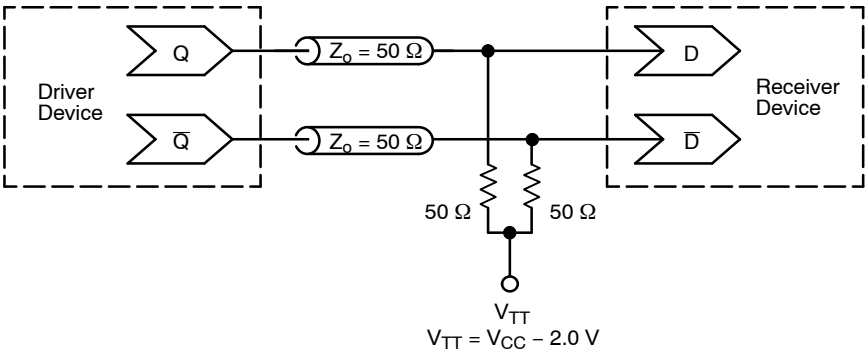

Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

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PACKAGE DIMENSIONS

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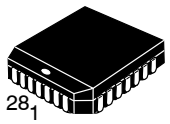

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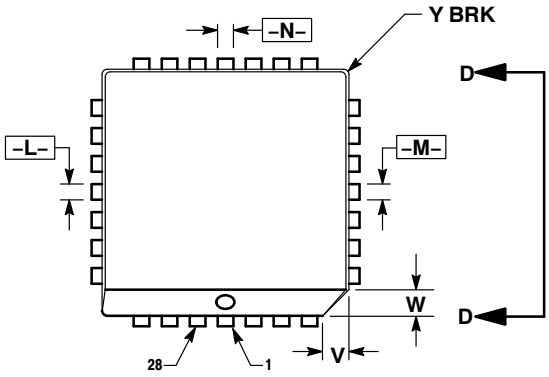

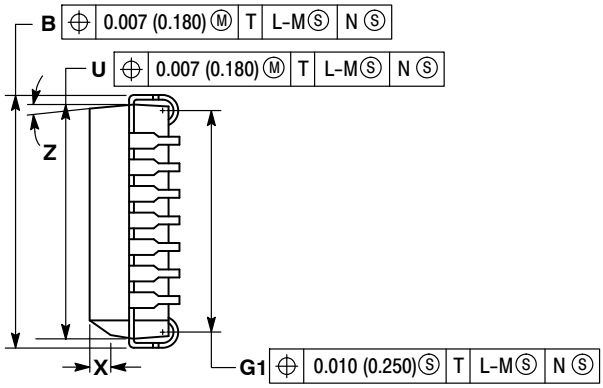

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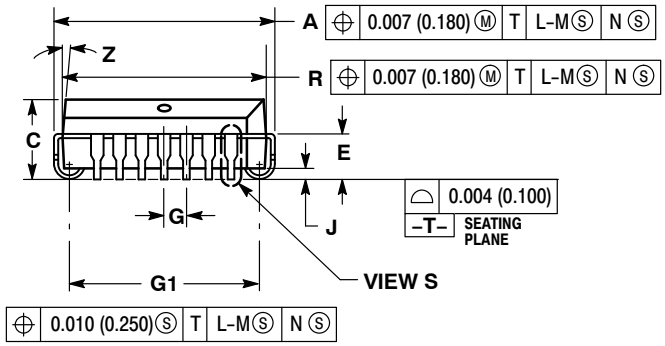
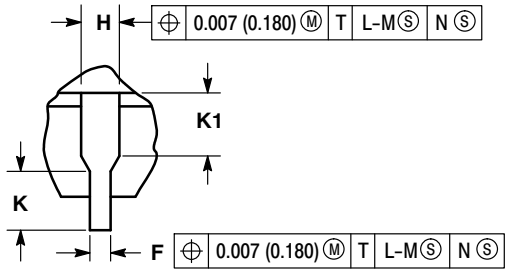


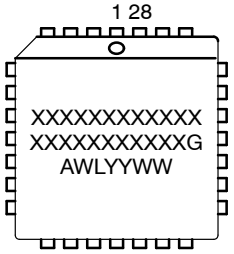


VIEW S

NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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